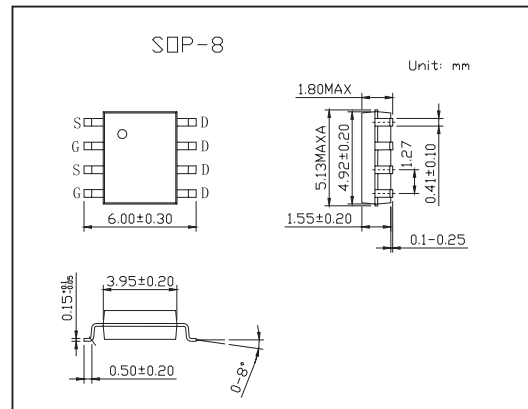
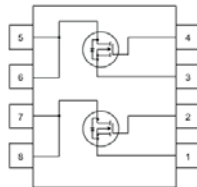


## 400V Dual N-Channel MOSFET

### KQS4901

#### ■ Features

- 0.45 A, 400 V.  $R_{DS(ON)} = 4.2 \Omega$  @  $V_{GS} = 10$  V
- Low gate charge (typical 5.8nC)
- Low  $C_{rss}$  (typical 5.0 Pf)
- Fast switching speed
- Improved dv/dt capability



#### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Drain to Source Voltage	$V_{bss}$	400	V
Drain Current Continuous ( $T_A=25^\circ\text{C}$ )	$I_D$	0.45	A
Drain Current Continuous ( $T_A=70^\circ\text{C}$ )		0.285	A
Drain Current Pulsed (Note 1)	$I_{DM}$	1.8	A
Gate-Source Voltage	$V_{GS}$	$\pm 25$	V
Peak Diode Recovery dv/dt ( Note 2)	dv/dt	4.5	V/ns
Power Dissipation ( $T_A=25^\circ\text{C}$ )	$P_D$	2	W
Power Dissipation ( $T_A=70^\circ\text{C}$ )		1.3	
Operating and Storage Temperature	$T_J, T_{STG}$	-55 to 150	$^\circ\text{C}$
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	62.5	$^\circ\text{C/W}$

## KQS4901

## ■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BVDSS	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μ A	400			V
Breakdown Voltage Temperature Coefficient	$\frac{\Delta BVDSS}{\Delta T_J}$	I <sub>D</sub> = 250 μ A, Referenced to 25°C		0.42		V/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 400 V, V <sub>GS</sub> = 0 V			1	μ A
		V <sub>DS</sub> = 320 V, T <sub>c</sub> = 125°C			10	
Gate-Body Leakage, Forward	I <sub>GSSF</sub>	V <sub>GS</sub> = 25 V, V <sub>DS</sub> = 0 V			100	nA
Gate-Body Leakage, Reverse	I <sub>GSSR</sub>	V <sub>GS</sub> = -25 V, V <sub>DS</sub> = 0 V			-100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μ A	2.0		4.0	V
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 0.225 A		3.2	4.2	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> = 35 V, I <sub>D</sub> = 0.225A (Note 3)		0.283		S
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1.0 MHz		160	210	pF
Output Capacitance	C <sub>oss</sub>			30	40	pF
Reverse Transfer Capacitance	C <sub>rss</sub>			5	6.5	pF
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 200V, I <sub>D</sub> = 0.45 A, R <sub>G</sub> = 25 Ω (Note 3,4)		5	20	ns
Turn-On Rise Time	t <sub>r</sub>			20	50	ns
Turn-Off Delay Time	t <sub>d(off)</sub>			20	50	ns
Turn-Off Fall Time	t <sub>f</sub>			35	80	ns
Total Gate Charge V <sub>GS</sub> =5V	Q <sub>g</sub>	V <sub>DS</sub> = 320 V, I <sub>D</sub> = 0.45 A, V <sub>GS</sub> =10V (Note 3,4)		5.8	7.5	nC
Gate-Source Charge	Q <sub>gs</sub>			0.53		nC
Gate-Drain Charge	Q <sub>gd</sub>			3.22		nC
Maximum Continuous Drain-Source Diode Forward Current	I <sub>S</sub>				0.45	A
Maximum Pulsed Drain-Source Diode Forward Current	I <sub>SM</sub>				1.8	A
Drain-Source Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 0.45 A			1.5	V
Diode Reverse Recovery Time	t <sub>rr</sub>	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 0.45 A (Not 3)		86		nS
Diode Reverse Recovery Charge	Q <sub>rr</sub>	diF/dt = 100 A/μ s		0.15		nC

Note:

- 1.Repetitive Rating: Pulse width limited by maximum junction temperature
- 2 I<sub>SD</sub> ≤ 0.45A, di/dt ≤ 200A/μ S, V<sub>DD</sub> ≤ BVDSS, starting T<sub>J</sub> = 25°C
- 3 Pulse Test :Pulse width ≤ 300 μ s, Duty cycle ≤ 2%
- 4 Essentially independent of operating temperature